

**RoHS T10B Series - DO-201**



**Description**

T10B Series are SIDACtor® devices designed protect baseband equipment such as modems, line cards, CPE and DSL from damaging overvoltage transients.

The series provides a robust and cost effective through-hole solution that enables equipment to comply with global regulatory standards

**Features and Benefits**

- Low voltage overshoot
- Low on-state voltage
- Does not degrade with use
- Fails short circuit when surged in excess of ratings
- High Surge Current Rating

**Applicable Global Standards**

- TIA-968-A
- ITU K.20/21 Enhanced Level
- ITU K.20/21 Basic Level
- GR 1089 Inter-building
- GR 1089 Intra-building
- IEC 61000-4-5
- YD/T 1082
- YD/T 993
- YD/T 950

**Agency Approvals**

Agency	Agency File Number
	E128662

**Pinout Designation**

Not Applicable

**Schematic Symbol**



**Electrical Characteristics**

Part Number	Marking	$V_{DRM}$ @ $I_{DRM}=5\mu A$	$V_S$ @ 100V/ $\mu s$	$I_H$	$I_S$	$I_T$	$V_T$ @ $I_T=2.2$ Amp	Capacitance @ 1MHz, 2V Bias
		V Min	V Max	mA Min	mA Max	A Max	V Max	pF
T10B080Bxx	T10B080B	70	125	120	800	2.2	4	60
T10B110Bxx	T10B110B	100	142	120	800	2.2	4	55
T10B140Bxx	T10B140B	120	178	120	800	2.2	4	48
T10B180Bxx	T10B180B	170	220	120	800	2.2	4	44
T10B220Bxx	T10B220B	200	275	120	800	2.2	4	41
T10B270Bxx	T10B270B	240	370	120	800	2.2	4	36
T10B080Exx	T10B080E	70	125	180	800	2.2	4	60
T10B110Exx	T10B110E	100	142	180	800	2.2	4	55
T10B140Exx	T10B140E	120	178	180	800	2.2	4	48
T10B180Exx	T10B180E	170	220	180	800	2.2	4	44
T10B220Exx	T10B220E	200	275	180	800	2.2	4	41
T10B270Exx	T10B270E	240	370	180	800	2.2	4	36

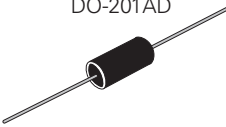
Notes:  
 - Absolute maximum ratings measured at  $T_A = 25^\circ C$  (unless otherwise noted).  
 - Devices are bi-directional (unless otherwise noted).  
 - **XX** Part Number Suffix: **'RP'** (Reel Pack), **Blank** (Bulk Pack), or **'60'** (Type 60 lead form, Bulk Pack)

**Surge Ratings**

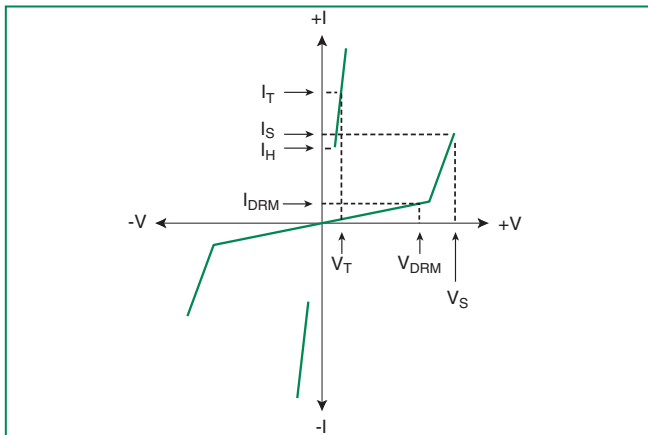
Series	I <sub>PP</sub>			I <sub>TSM</sub> 50/60 Hz	di/dt
	8x20 <sup>1</sup> 1.2x50 <sup>2</sup>	5x310 <sup>1</sup> 10x700 <sup>2</sup>	10x1000 <sup>1</sup> 10x1000 <sup>2</sup>		
	A min	A min	A min		
B	250	125	100	30	500

Notes:  
 1 Current waveform in  $\mu\text{s}$  - Peak pulse current rating (I<sub>pp</sub>) is repetitive and guaranteed for the life of the product.  
 2 Voltage waveform in  $\mu\text{s}$  - I<sub>pp</sub> ratings applicable over temperature range of -40°C to +85°C  
 - The device must initially be in thermal equilibrium with -40°C ≤ T<sub>j</sub> ≤ +150°C

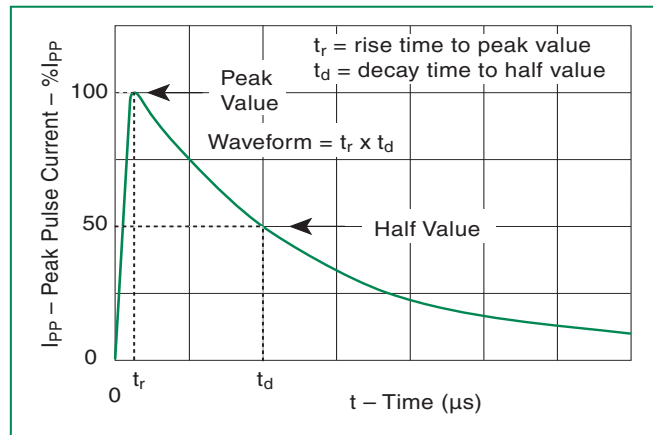
**Thermal Considerations**

Package	Symbol	Parameter	Value	Unit
DO-201AD 	T <sub>J</sub>	Operating Junction Temperature Range	-40 to +150	°C
	T <sub>S</sub>	Storage Temperature Range	-65 to +150	°C
	R <sub>θJA</sub>	Thermal Resistance: Junction to Ambient	120	°C/W

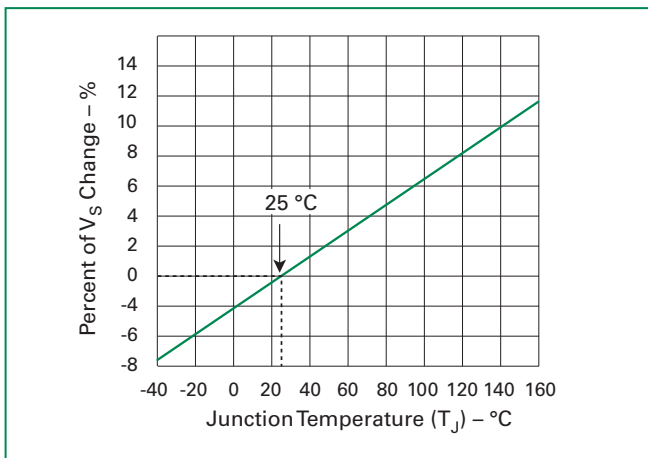
**V-I Characteristics**



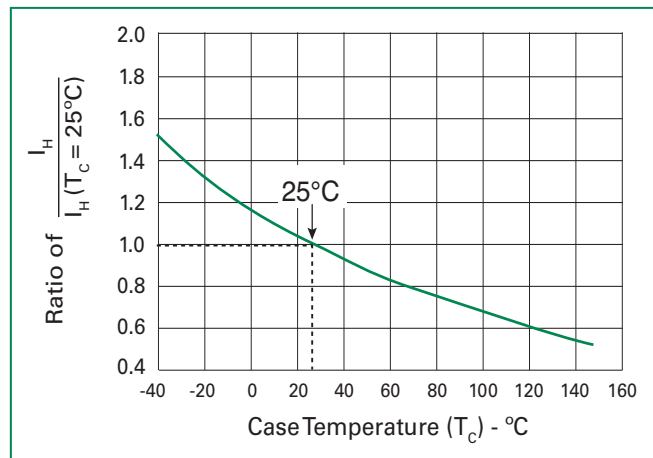
**t<sub>r</sub> x t<sub>d</sub> Pulse Waveform**



**Normalized V<sub>S</sub> Change vs. Junction Temperature**



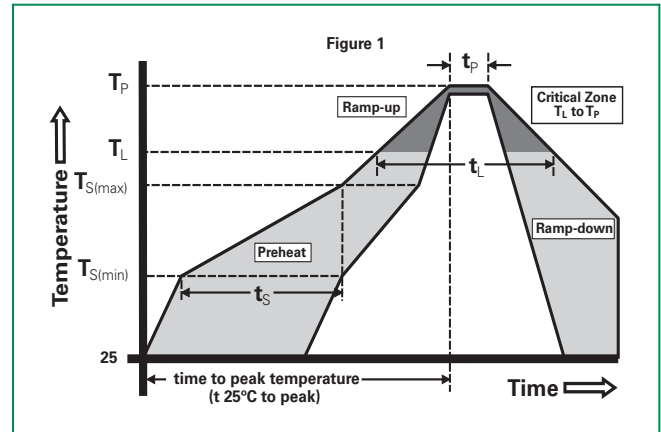
**Normalized DC Holding Current vs. Case Temperature**



T10B Series

### Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max ( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/sec. Max.
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature ( $T_L$ ) (Liquidus)	+217°C
	-Temperature ( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max.
Do not exceed		+260°C



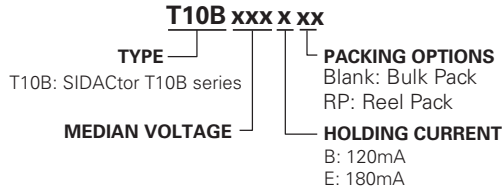
### Physical Specifications

<b>Lead Material</b>	Copper Alloy
<b>Terminal Finish</b>	100% Matte-Tin Plated
<b>Body Material</b>	UL recognized epoxy meeting flammability classification 94V-0

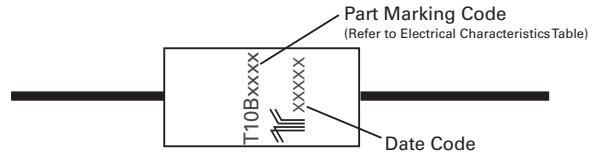
### Environmental Specifications

<b>High Temp Voltage Blocking</b>	80% Rated $V_{DRM}$ ( $V_{AC Peak}$ ) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
<b>Temp Cycling</b>	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
<b>Biased Temp &amp; Humidity</b>	52 $V_{DC}$ (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
<b>High Temp Storage</b>	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
<b>Low Temp Storage</b>	-65°C, 1008 hrs.
<b>Thermal Shock</b>	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
<b>Autoclave (Pressure Cooker Test)</b>	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
<b>Resistance to Solder Heat</b>	+260°C, 30 secs. MIL-STD-750 (Method 2031)
<b>Moisture Sensitivity Level</b>	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

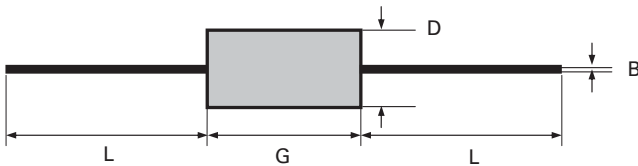
**Part Numbering**



**Part Marking**



**Dimensions — DO-201AD**

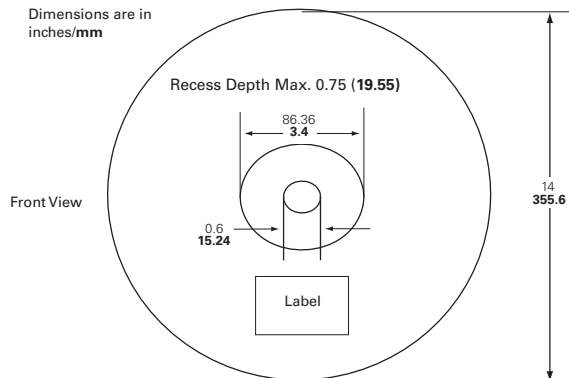
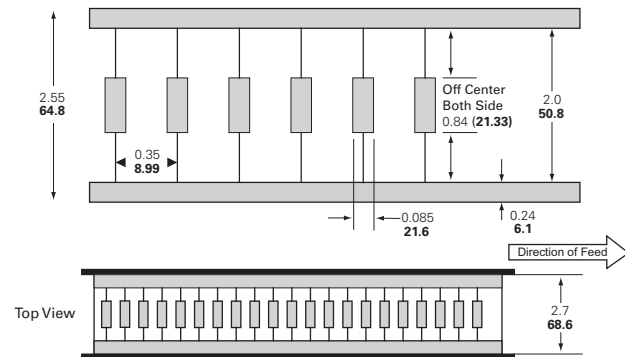


Dimension	Inches		Millimeters	
	MIN	MAX	MIN	MAX
<b>B</b>	0.028	0.042	0.711	1.067
<b>D</b>	0.190	0.205	4.826	5.207
<b>G</b>	0.360	0.375	9.146	9.527
<b>L</b>	1		25.4	

**Packing Options**

Package Type	Description	Quantity	Added Suffix	Industry Standard
T10B	DO-201AD Tape and Reel Pack	1000	RP	EIA-RS-296-D
	DO-201AD Bulk Pack	500	N/A	N/A

**Tape and Reel Specification — DO-201AD**



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